

ABSTRACT OF THE DISCLOSURE

A method of qualifying a process tool includes steps of: (a) finding a plurality of pre-scan defect locations on a surface of a semiconductor wafer; (b) subjecting the semiconductor wafer to processing by the process tool; (c) finding a plurality of post-scan defect locations on the surface of the semiconductor wafer; and (d) calculating a plurality of defect locations added by the process tool from the pre-scan defect locations and the post-scan defect locations.